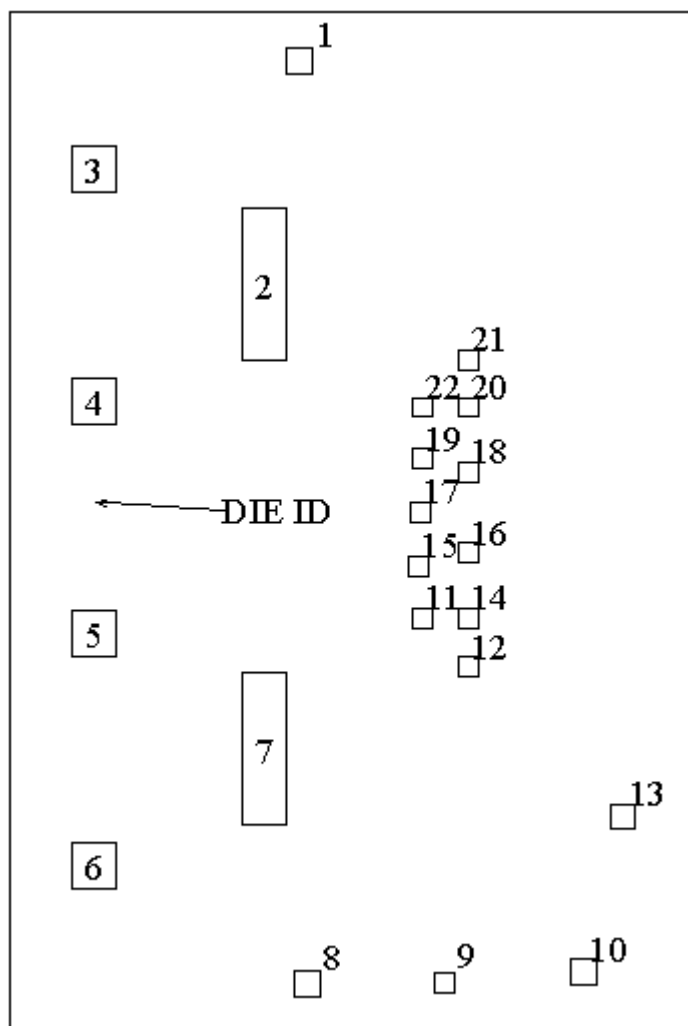


LM1577K-ADJ MD8 MW8
SIMPLE SWITCHER® STEP-UP VOLTAGE REGULATOR

July 06,2007

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1577D	Bond Pad Opening Size (min)	80µm x 80µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	GOLD BACK
Die Size (Drawn)	2743µm x 4089µm 108.0mils x 161.0mils	Back Side Connection	GND
Thickness	254µm Nominal		
Min Pitch	186µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D-Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
VIN	1	-215	1851	102	x	102
SWITCH	2	-355	951	180	x	608
GND	3	-1039	1416	180	x	180
GND	4	-1039	486	180	x	180
GND	5	-1039	-444	180	x	180
GND	6	-1039	-1374	180	x	180
SWITCH	7	-355	-909	180	x	608
COMP	8	-187	-1851	102	x	102
NC	9	362	-1843	80	x	80
FB	10	922	-1803	102	x	102
NC	11	276	-381	80	x	80
NC	12	462	-581	80	x	80
GND	13	1078	-1178	102	x	102
NC	14	462	-381	80	x	80
NC	15	263	-174	80	x	80
NC	16	462	-124	80	x	80
NC	17	269	40	80	x	80
NC	18	462	204	80	x	80
NC	19	275	254	80	x	80
NC	20	462	461	80	x	80
NC	21	462	652	80	x	80
NC	22	275	461	80	x	80

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Notes

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